

30V N-Channel Enhancement Mode Power MOSFET

Description

EMQ40N03T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

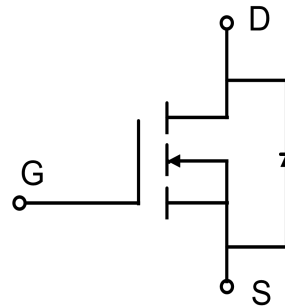
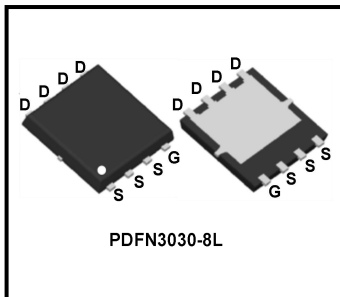
Features

- $V_{DS} = 30V$, $I_D = 70A$
 $R_{DS(on)} < 5.5m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(on)} < 9.0m\Omega$ @ $V_{GS} = 4.5V$
- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed

Applications

- Power Management Switches
- DC/DC Converter

Schematic



Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ¹	$T_C = 25^\circ C$	I_D	70	A
	$T_C = 100^\circ C$		47	
Pulsed Drain Current ²		I_{DM}	280	A
Single Pulse Avalanche Energy ³		EAS	61	mJ
Total Power Dissipation ⁴	$T_C = 25^\circ C$	P_D	48	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ¹	$R_{\theta JA}$	60	°C/W
Thermal Resistance from Junction-to-Case ¹	$R_{\theta JC}$	2.6	°C/W

Electrical Characteristics T_c = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30	-	-	V
Gate-body Leakage current		I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T _J =25°C	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V	-	-	1	μA
	T _J =55°C			-	-	5	
Gate-Threshold Voltage		V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.2	1.6	2.5	V
Drain-Source On-Resistance ²		R _{DS(on)}	V _{GS} = 10V, I _D = 20A	-	4.3	5.5	mΩ
			V _{GS} = 4.5V, I _D = 10A	-	6.5	9.0	
Forward Transconductance ²		g _{fs}	V _{DS} =5V , I _D =30A	-	60	-	S
Dynamic Characteristics							
Input Capacitance		C _{iss}	V _{DS} = 15V, V _{GS} =0V, f =1MHz	-	2115	-	pF
Output Capacitance		C _{oss}		-	290	-	
Reverse Transfer Capacitance		C _{rss}		-	230	-	
Switching Characteristics							
Gate Resistance		R _g	V _{DS} = 0V, V _{GS} =0V, f =1MHz	-	2.0	-	Ω
Total Gate Charge		Q _g	V _{GS} = 4.5V, V _{DS} = 15V, I _D = 15A	-	18	-	nC
Gate-Source Charge		Q _{gs}		-	6	-	
Gate-Drain Charge		Q _{gd}		-	5.5	-	
Turn-On Delay Time		t _{d(on)}	V _{GS} =10V, V _{DD} = 15V, R _G = 3.3Ω, I _D = 15A	-	9.8	-	ns
Rise Time		t _r		-	13	-	
Turn-Off Delay Time		t _{d(off)}		-	40	-	
Fall Time		t _f		-	9	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage ²		V _{SD}	I _S = 1A, V _{GS} = 0V	-	-	1	V
Continuous Source Current ^{1,5}		I _S	V _G =V _D =0V , Force Current	-	-	70	A

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 35A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

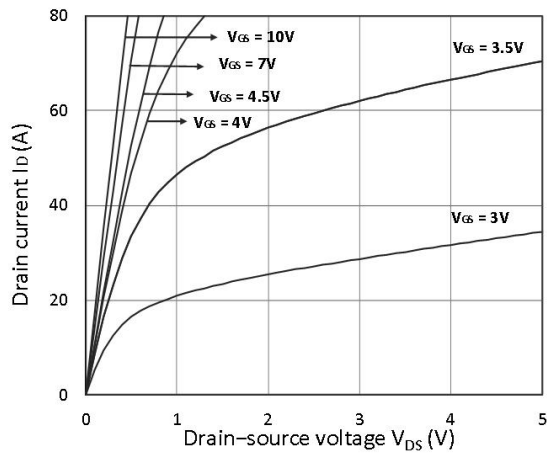


Figure 1. Output Characteristics

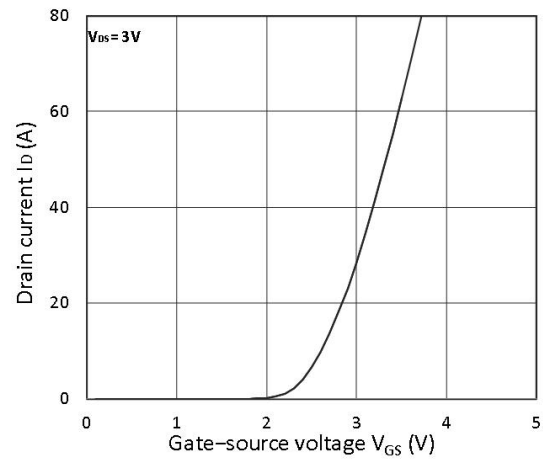


Figure 2. Transfer Characteristics

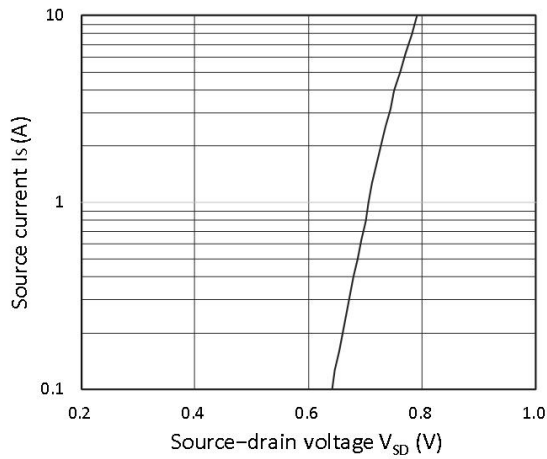


Figure 3. Forward Characteristics of Reverse

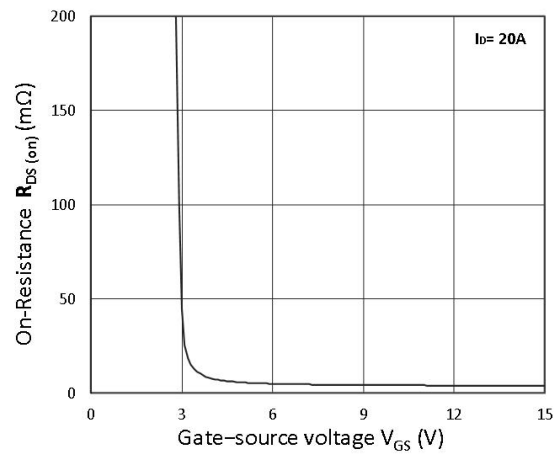


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

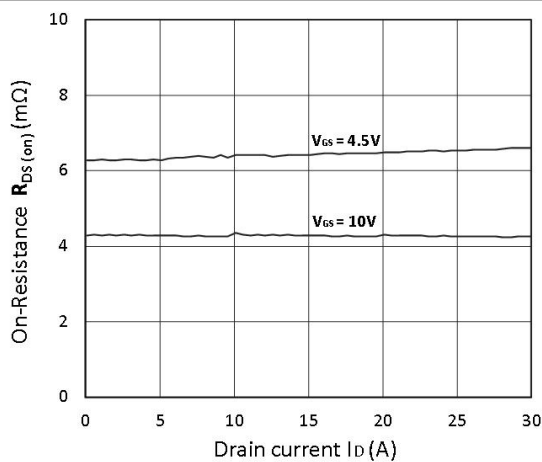


Figure 5. $R_{DS(ON)}$ vs. I_D

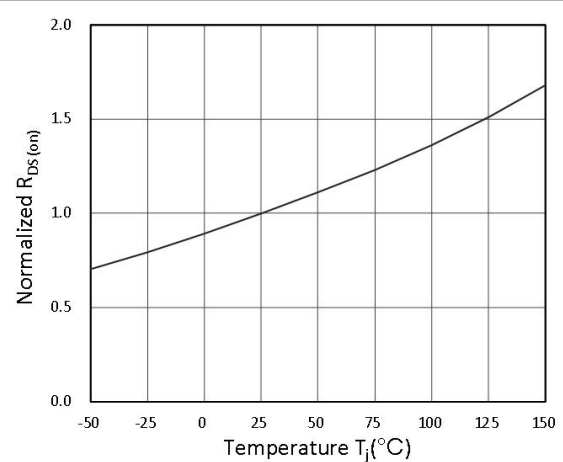


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

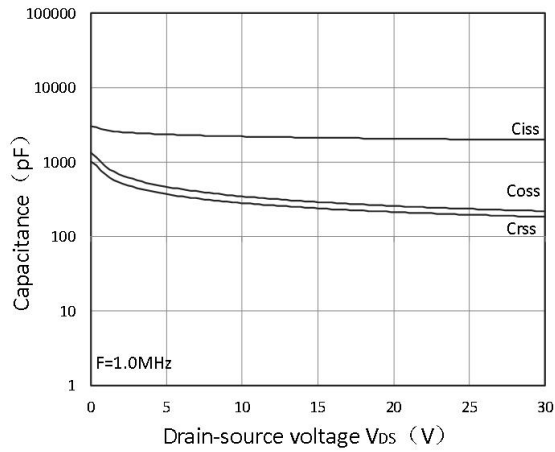


Figure 7. Capacitance Characteristics

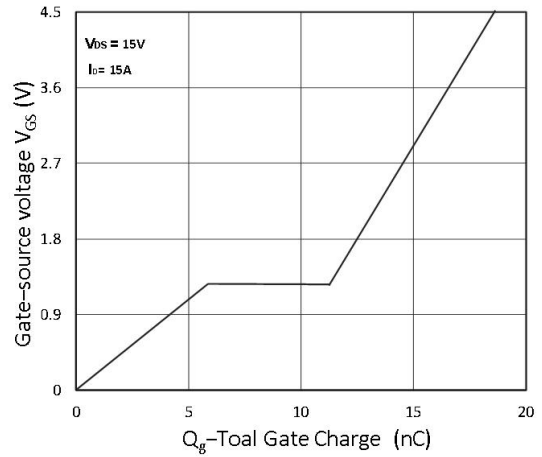


Figure 8. Gate Charge Characteristics

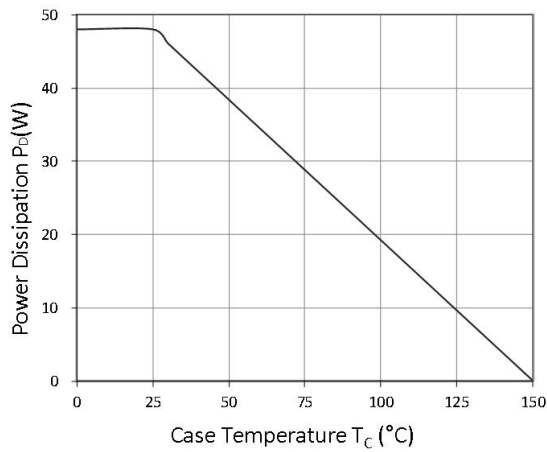


Figure 9. Power Dissipation

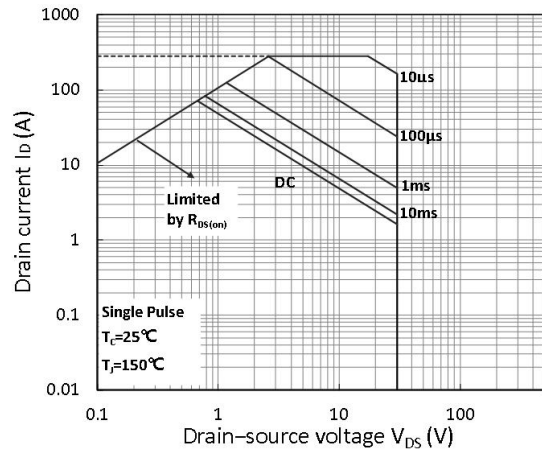


Figure10. Safe Operating Area

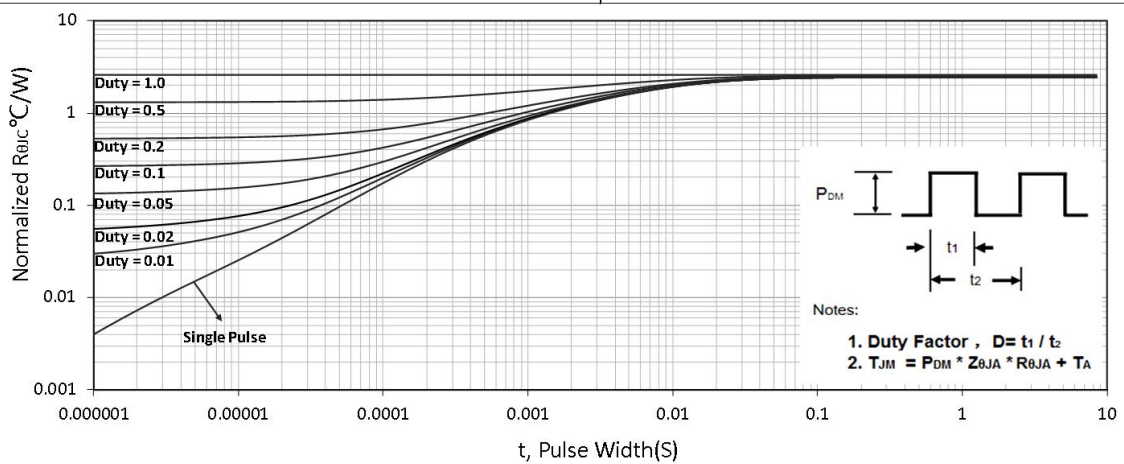


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

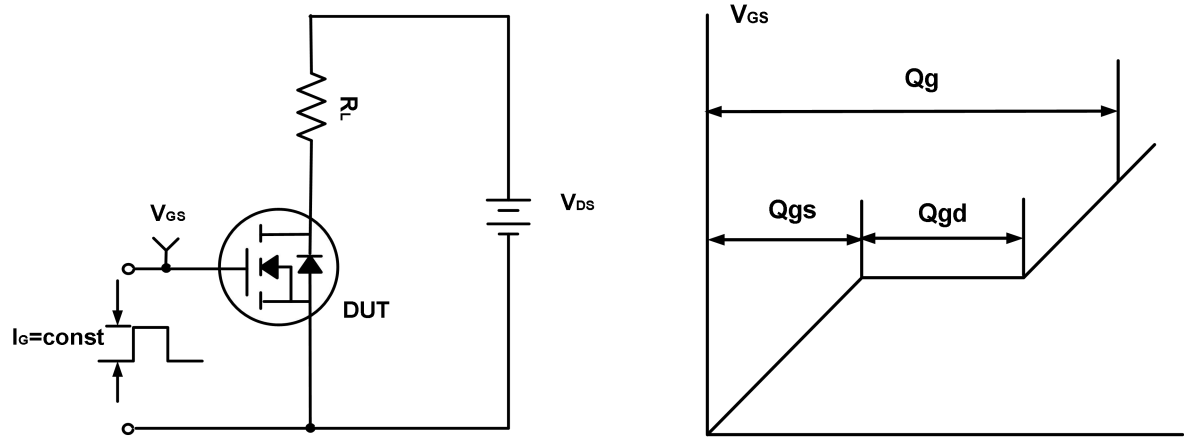


Figure A. Gate Charge Test Circuit & Waveforms

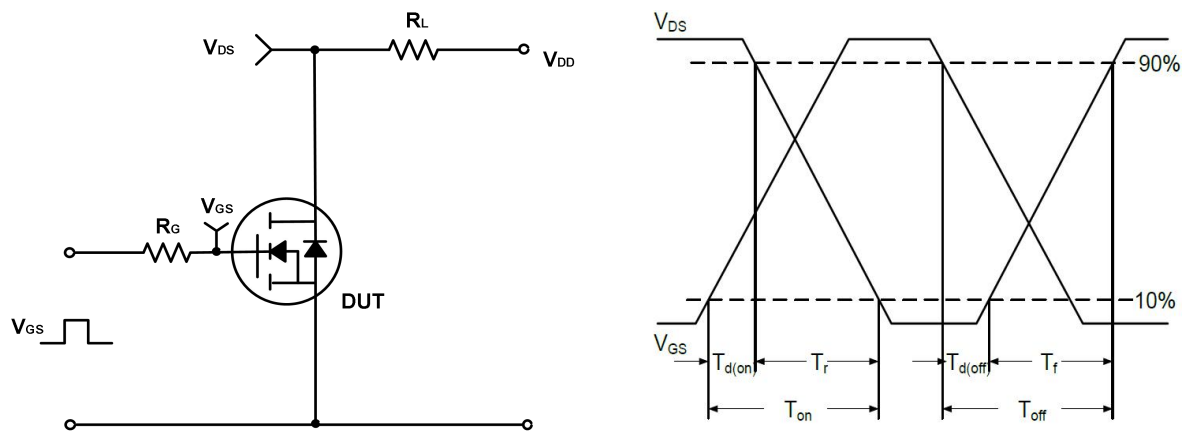


Figure B. Switching Test Circuit & Waveforms

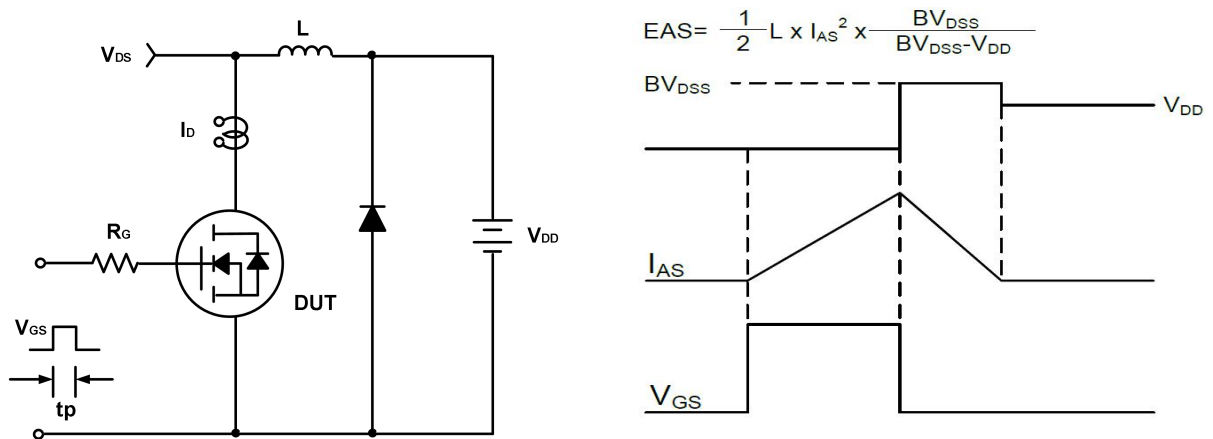


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Mechanical Dimensions for PDFN3030-8L

PACKAGE OUTLINE			
SYMBOL	MM		
	MIN	MAX	
A	0.65	0.90	
A1	0.10	0.25	
D	2.90	3.25	
D1	2.25	2.69	
E	2.90	3.20	
E1	3.00	3.60	
E2	1.35	2.20	
b	0.20	0.40	
e	0.65BSC		
L	0.15	0.50	
L1	0.13BSC		
L2	0.00	0.20	
H	0.15	0.65	
θ	0°	14°	

Revision History

No.	Version	Date	Revision Item	Request	Function and characteristic checking	Package dimension checking	Typos checking
1	1.0	2019-11-08	Released Version	Qi Shu Kun	Qi Shu Kun	Liu Jia Ying	Liu Jia Ying